



Mr. Lemnios is the MIT Lincoln Laboratory Chief Technology Officer (CTO). He is responsible for coordinating technology strategy across the Laboratory and for establishing and growing strategic relationships outside of the Laboratory to support current and future Laboratory missions. This includes collaboration with MIT Campus to develop and leverage research projects in support of defense and related activities. Mr. Lemnios is a member of the Director's Office Staff and Laboratory Steering Committee.

From March 2005 to July 2006, Mr. Lemnios was Assistant Division Head of the MIT Lincoln Laboratory Solid State Division, a member of the Laboratory's Senior Management Council and Co-Chair of the Laboratory's New Technology Initiative (NTI) Board.

From July 2003 to February 2005, Mr. Lemnios was the Director of the Defense Advanced Research Projects Agency (DARPA) Microsystems Technology Office (MTO). In that position, Mr. Lemnios was responsible for developing and implementing the strategic vision and technical plans for the office and for transitioning those elements to the Department of Defense. That included developing future research thrusts, analyzing and evaluating program proposals and engagements with commercial, academic organizations and representing DARPA on various national committees

From April 2002 to July 2003, Mr. Lemnios was the Deputy Director of the Information Processing Technology Office (IPTO) where he was instrumental in developing and launching a new DARPA direction in Cognitive Systems. In this position he shared responsibility with the Office Director for all technical, administrative and financial aspects of the Office.

From 1997 to 2002, Mr. Lemnios was a Senior Staff member of the Solid State Division at MIT Lincoln Laboratory. In that capacity, he led efforts to develop novel system applications for a broad range of materials including CMOS/SOI, SiC, GaN, AlGaIn and GaAs. He also developed and inserted advanced microelectronics technology into performance-driven DoD applications.

Prior to joining MIT Lincoln Laboratory, Mr. Lemnios was the Assistant Director of the Electronics Technology Office, also at DARPA, and led the development and insertion of advanced microelectronics into many DoD systems. In addition to being the DoD Program Manager for SEMATECH, Mr. Lemnios sponsored the development of the first 0.25 μm CMOS/bulk and SOI manufacturing technology base, established the flexible cluster-based semiconductor manufacturing tool approach and demonstrated the first 75 GHz GaAs and 150 GHz InP HBT technology base. His further support of wideband and high linearity A/D converters resulted in key system insertions for critical DoD applications.

Mr. Lemnios has also held various positions within industry at Hughes Aircraft Company, Westinghouse Electric Corporation and Ford Microelectronics, Inc. that led to the development and demonstration of advanced GaAs MMIC components.

Mr. Lemnios has served on numerous DoD, industry and academic committees. He was the General Chair of GOMAC-04 and has served on the Steering Committee or Technical program Committee of many domestic and international conferences and workshops.

Mr. Lemnios received his BSEE from the University of Michigan and his MSEE from Washington University in St. Louis. Mr. Lemnios has authored over 40 papers, holds 4 patents in advanced GaAs device and MMIC technology and is a Senior Member of the IEEE.